

# Specification of Thermoelectric Module

**TEC2-127-63-08**

## Description

The TEC2-127-63-08 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-63 couples module in size of 40 mm × 40 mm (top) / 40 mm × 40 mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

## Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

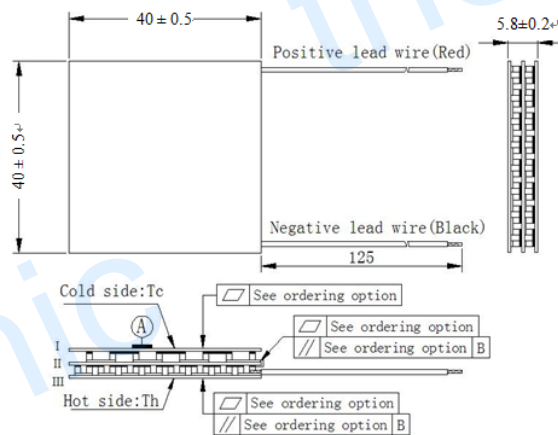
## Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

## Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	90	100	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	16.1	17.6	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (Amps)	8.0	8.0	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	51.7	55.6	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	1.59	1.71	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

## Geometric Characteristics Dimensions in millimeters



## Sealing Option

### A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)(AIO)
2. Aluminum Nitride (AlN)

### D. Ceramics Surface Options:

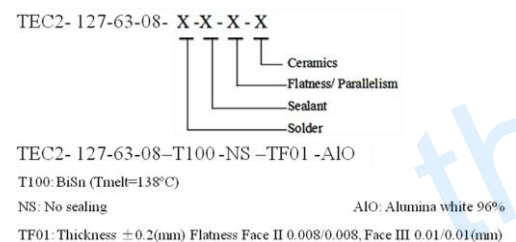
1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

## Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 5.8±0.2	0: Face II 0.010/0.010, Face III 0.015/0.015	125±1/Specify
TF	1: 5.8±0.15	1: Face II 0.008/0.008, Face III 0.010/0.010	125±1/Specify
TF	2: 5.8±0.1	2: Face II 0.005/0.005, Face III 0.008/0.008	125±1/Specify

Eg. TF01: Thickness 5.8±0.2(mm) and Face II 0.008/0.008, Face III 0.01/0.01

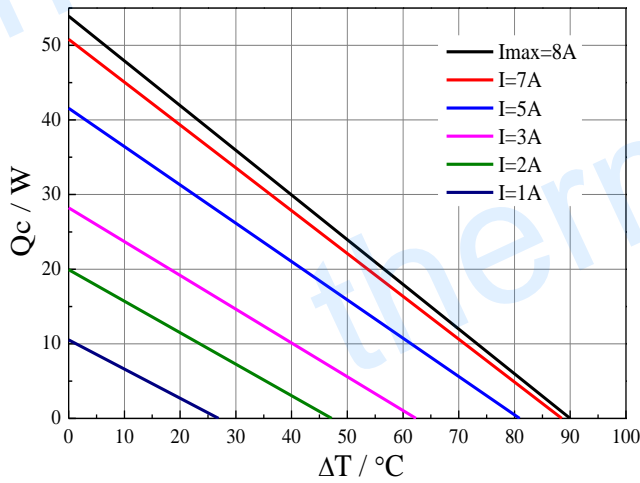
## Naming for the Module



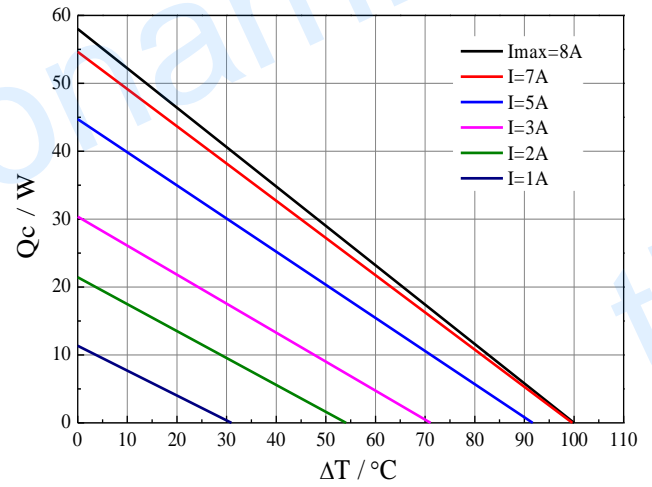
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## TEC2-127-63-08

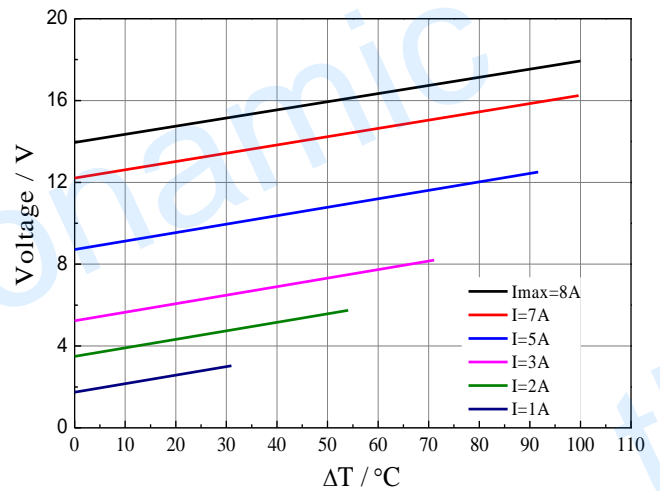
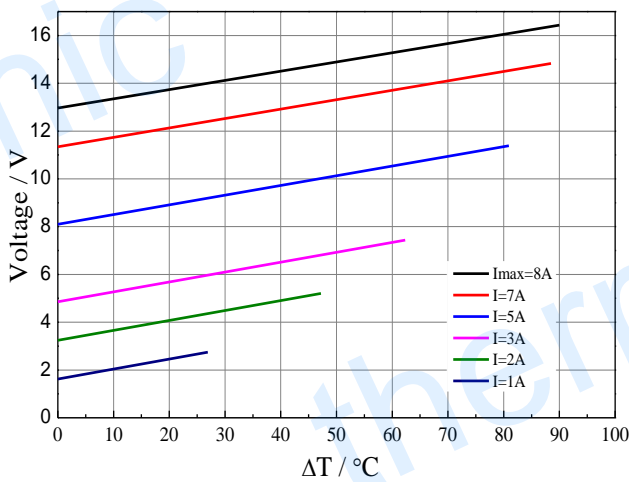
Performance Curves at  $T_h=27\text{ }^\circ\text{C}$



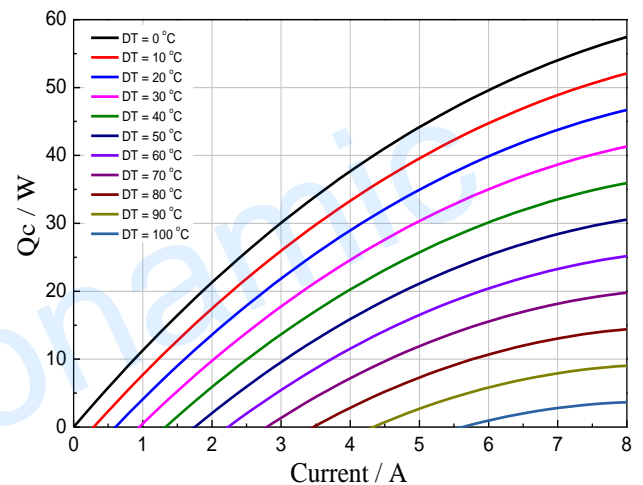
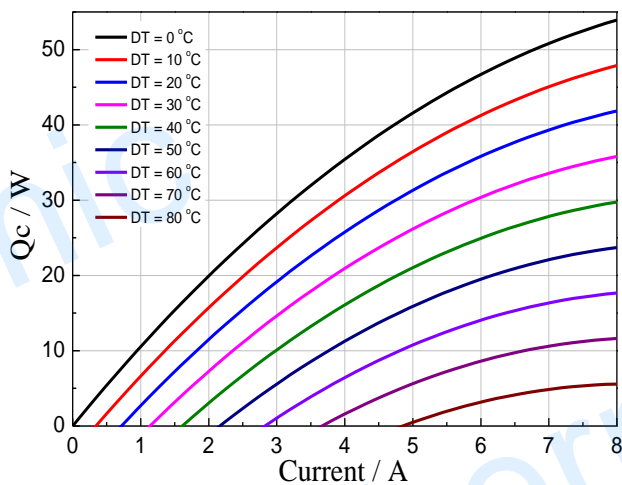
Performance Curves at  $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph  $Q_c = f(\Delta T)$



Standard Performance Graph  $V = f(\Delta T)$

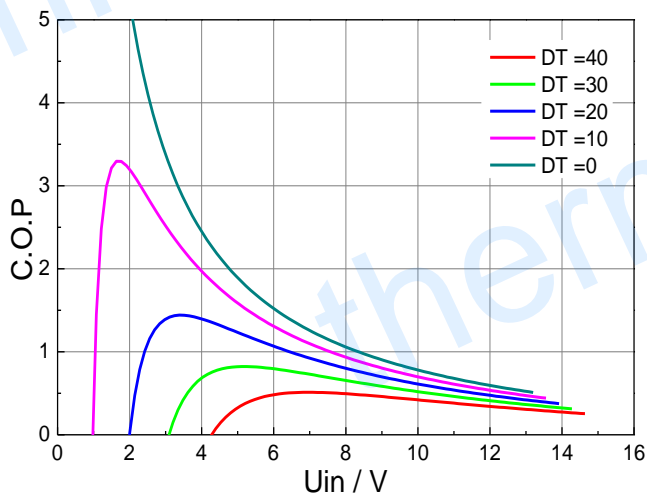


Standard Performance Graph  $Q_c = f(V)$

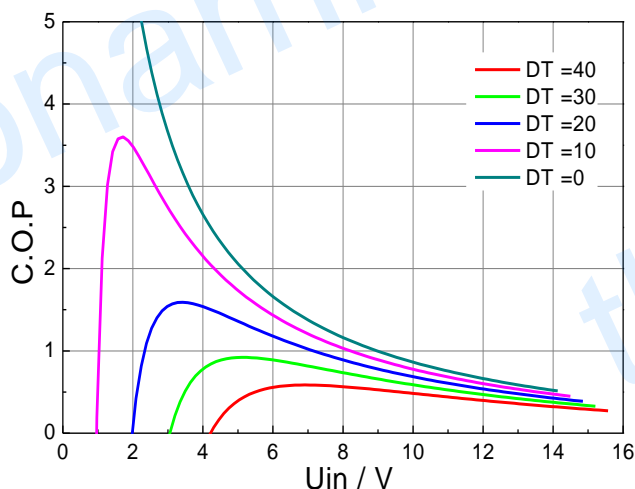
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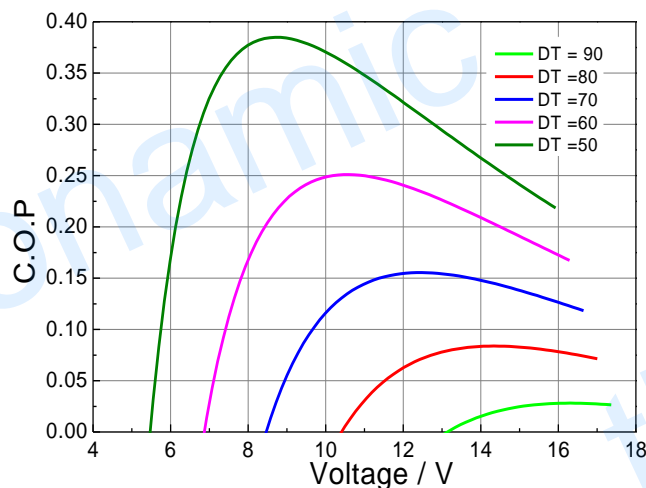
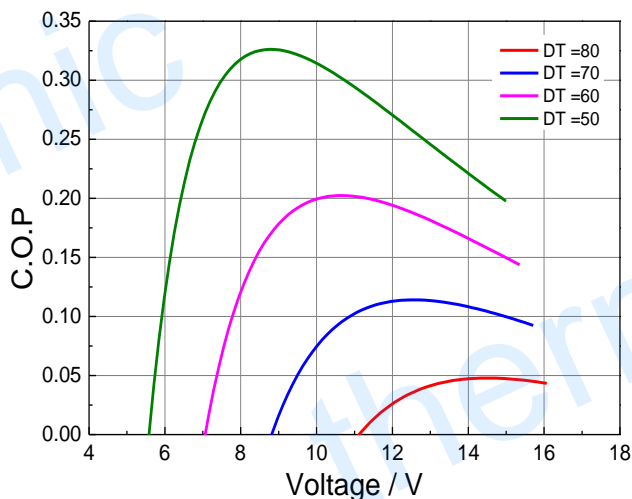
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 40 °C



Standard Performance Graph COP = f(V) of DT ranged from 50 to 80/90 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Caution

- Cold side of the module stuck on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.